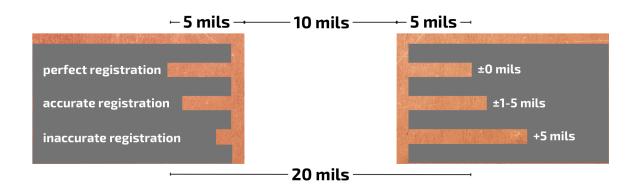
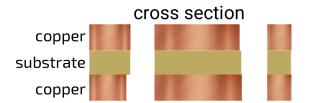
# **Registration** Accuracy





# **Accurate Registration** ±1-5 mil tolerance

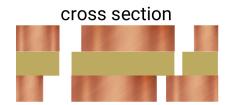




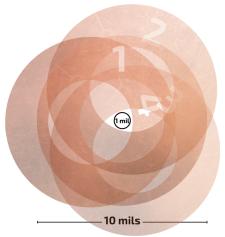




### Inaccurate Registration +5 mil tolerance



top view





# **Registration** Single-Core — Front-to-Back

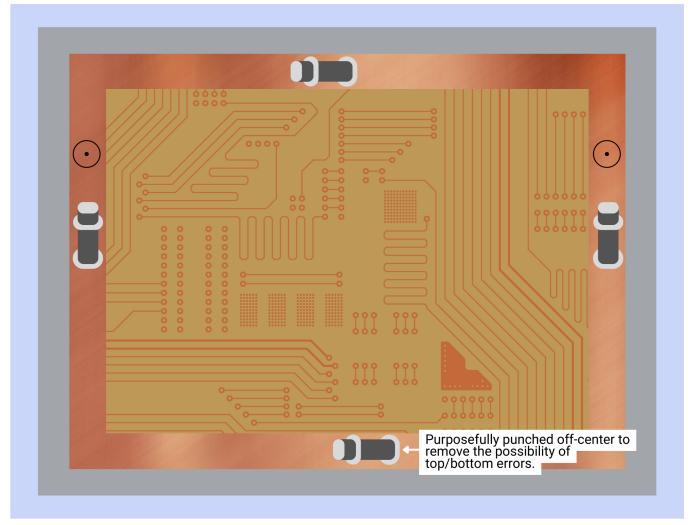
LDI – LASER Direct Imaging
 Front-to-back registration can be as tight as 10μm leaving very little error within a single core—providing excellent layer to layer registration.



# **Registration** Multi-Core — Core-to-Core

### **PEP - Post-Etch-Punch** - ±3-5 mils accuracy

- Also known as hard-pinning
  This process uses imaged & etched targets (fiducials) and up to 8 camera systems to calculate center of the targets. Aligning the image to center and "punches" 4 slotted tooling holes into each core to place hard-pins into.
- This type of tooling is featured in most board shops, both foreign and domestic.
   Most Flexible offers high accuracy at a lower cost than most registration types.



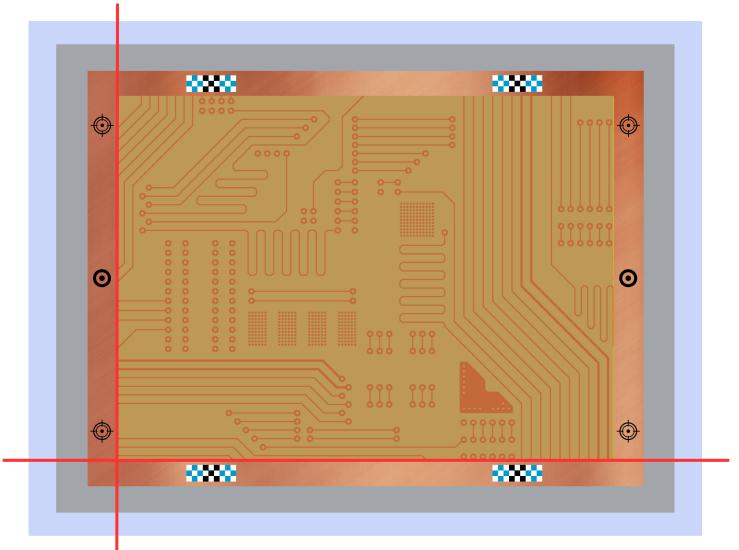
Registration Pins – flat on two sides to decrease mis-alignment

• PEP Target - Post-Etch-Punch



## **Registration** Multi-Core — Core-to-Core

- Optical/Welded alternate pin-less method ±1-3 mils accuracy
   In use since 1999 slowly on the rise worldwide but mostly used in Asia, where PCB fabrication is newer.
  - Most Accurate though HDI and/or high-layer count boards are often done using hard-pin registration, pin-less optical/welded registration offers significant benefits for accurate alignment with tight spaces, traces and hole density.



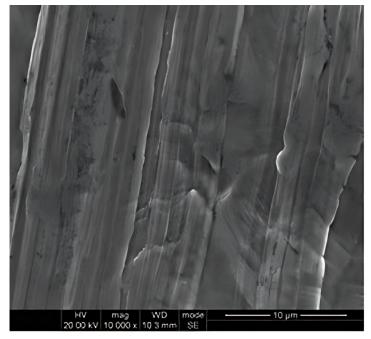
**LASER Placement Lines** 

- Corner Targets 4x Top & Bottom for layer measurement
- Weld Coupons − 4x

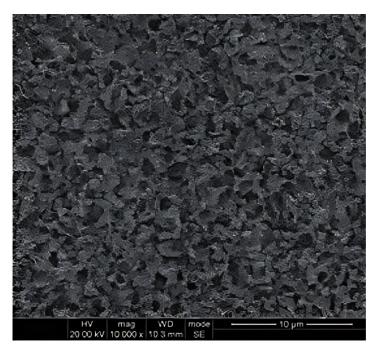


# Oxide SEM-Before & After

Scanning Electron Microscopy photos of a board before and after oxide process.



before **Smooth Copper** 



after Oxided (roughened) Copper

